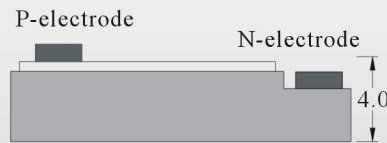
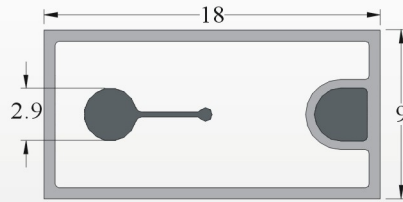




Product Introduction  
**LPABG18A**



Unit: mil

**LPABG18A**

**Mechanical Specifications**

Dimensions

Chip Size: 9mil x 18mil

( $230 \pm 20 \mu\text{m} \times 460 \pm 20 \mu\text{m}$ )

Chip Thickness: 4mil( $100 \pm 10 \mu\text{m}$ )

Pad Size: 2.9mil( $72 \pm 10 \mu\text{m}$ )

Metallization

P Electrode: Au

N Electrode: Au

**Typical Electrical/Optical Characteristics**

| Parameter           | Symbol         | Condition            | Min. | Typ. | Max. | Unit |
|---------------------|----------------|----------------------|------|------|------|------|
| Forward Voltage     | V <sub>f</sub> | I <sub>f</sub> =20mA | 2.8  | ---  | 3.6  | V    |
| Reverse Current     | I <sub>r</sub> | V <sub>r</sub> =5V   | ---  | ---  | 1    | μA   |
| Dominant Wavelength | λ <sub>d</sub> | I <sub>f</sub> =20mA | 445  | ---  | 475  | nm   |
| Full Width Half Max | Δλ             | I <sub>f</sub> =20mA | ---  | ---  | 30   | nm   |
| Radiant Flux        | P <sub>o</sub> | I <sub>f</sub> =20mA | 21.5 | ---  | 31   | mW   |

**Standard Bin Table**

| Po(mW) \ Wd(nm) | 447.5–450 | 450–452.5 | 452.5–455 | 455–457.5 | 457.5–460 | 460–462.5 |
|-----------------|-----------|-----------|-----------|-----------|-----------|-----------|
| 29–31           | FBOX      | GAOX      | GBOX      | HAOX      | HBOX      | IAOX      |
| 27.5–29         | FBNX      | GANX      | GBNX      | HANX      | HBNX      | IANX      |
| 26–27.5         | FBMX      | GAMX      | GBMX      | HAMX      | HBMX      | IAMX      |
| 24.5–26         | FBLX      | GALX      | GBLX      | HALX      | HBLX      | IALX      |
| 23–24.5         | FBKX      | GAKX      | GBKX      | HAKX      | HBKX      | IAKX      |
| 21.5–23         | FBJX      | GAJX      | GBJX      | HAJX      | HBJX      | IAJX      |

**Notes:**

- The Electrical/Optical Characteristics are measured with LatticePower electro-optical equipment at T<sub>a</sub>=25°C without an encapsulant.
- GaN LED chips are electrostatic sensitive, so ESD protection during chip handling is recommended.
- We welcome customer's enquiries for special requirements.